

**In the Claims:**

**Please cancel claims 10-27 without prejudice or disclaimer.**

**Please rewrite claims 1, 2 and 9, and add new claim 28 as follows:**

1. (Currently Amended) A composite member comprising different members of a ceramic base and a metallic member which are bonded to each other, wherein an active metal foil is disposed on the surface of the ceramic base and a solder material comprising Au is disposed directly on the active metal foil, the active metal foil and the solder material are heated to form a bonding layer, the metallic member is disposed on the surface of the bonding layer, and these are pressed and heated to bond the bonding layer and the metallic member through solid phase bonding.

*A1* 8. (Currently Amended) A composite member comprising different members of a ceramic base and a metallic member which are bonded to each other, wherein an active metal foil is disposed on the surface of the ceramic base and a solder material comprising an Au-Ag alloy is disposed directly on the active metal foil, the active metal foil and the solder material are heated to form a bonding layer, the metallic member is disposed on the surface of the bonding layer, and these are pressed and heated to bond the bonding layer and the metallic member through solid phase bonding.

*9.* (Original) A composite member according to claim 8, wherein the content of Ag in the Au-Ag alloy is 0.5-80 wt%.

*2-4.* (Original) A composite member according to claim 1, wherein an electrical conductor comprising Mo, W or an alloy of Mo and W is embedded in the ceramic base so

that a part of the surface of the electrical conductor is exposed to the exterior of the ceramic base.

*3* 7. (Original) A composite member according to claim 1, wherein the material of the ceramic base is at least one material selected from the group consisting of aluminum nitride, silicon nitride, alumina, zirconia, magnesia, spinel and silicon carbide.

*4* 8. (Original) A composite member according to claim 1, wherein the material of the metallic member is at least one material selected from the group consisting of Ni, Co, Fe and Cr.

*5* 1. (Original) A composite member according to claim 1, wherein the material of the metallic member is an alloy comprising as a main constituting element at least one material selected from the group consisting of Ni, Co, Fe and Cr.

*6* 8. (Original) A composite member according to claim 1, wherein the material of the active metal foil is at least one material selected from the group consisting of Ti, Nb, Hf and Zr.

*7* 1. (Currently Amended) A composite member according to claim 1, wherein the composite member which is used as a susceptor for disposing a semiconductor wafer.

Claims 10-27 (Cancelled)

1028. (New) A composite member, comprising:

a ceramic base;

an electrical conductor comprising Mo, W or an alloy of Mo and W embedded in said ceramic base such that a part of a surface of the electrical conductor is exposed to the exterior of the ceramic base; and

a metallic member bonded to the ceramic base, wherein

an active metal foil is disposed on the surface of the ceramic base and a solder material comprising Au is disposed on the active metal foil, the active metal foil and the solder material are heated to form a bonding layer, the metallic member is disposed on the surface of the bonding layer, and these are pressed and heated to bond the bonding layer and the metallic member through solid phase bonding.

